

# ISL55110\_11EVAL1Z, ISL55110\_11EVAL2Z

Evaluation Board User's Manual

AN1283  
Rev 0.00  
February 13, 2007

## Before Getting Started

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Scope Probe Test Points (TP) are provisioned across all inputs, outputs and VDD/VH to ground.

## SCOPE PROBE CONNECTIONS

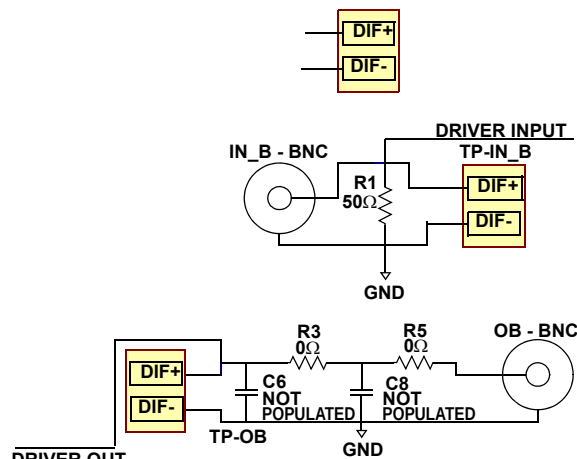


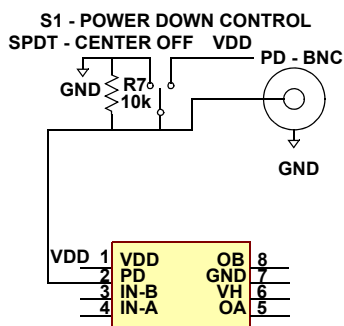
FIGURE 1. DUAL 1" SPACED PINS ARE PLACED ON THE EVALUATIONS BOARDS FOR LEADLESS ACTIVE PROBE CONNECTIONS

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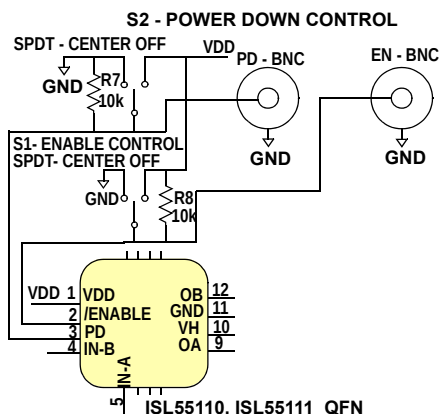
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ISL55110, ISL55111\_TSSOP

**FIGURE 2. TSSOP AND QFN EVALUATION BOARDS HAVE THE SAME POWER DOWN CIRCUITRY**

Finally the center off position provides a means of connecting a repetitive signal source to the PD input. This is so that the user can observe Power Down Enable/Disable timing. An important note to remember when using the PD - BNC: 1) Place the switch in Center-Off position. 2) The PD input is referenced to VDD and ground.



ISL55110, ISL55111\_QFN

**FIGURE 3. QFN PACKAGES HAVE BOTH POWER DOWN AND OUTPUT ENABLE DIGITAL INPUTS**

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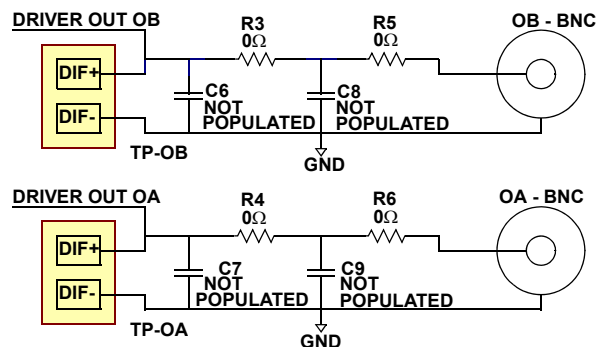
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Schematics are drawn with physical location in mind. Any changes in electrical circuitry will be updated in this document as needed.

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**FIGURE 4. CUSTOM LOAD COMPONENTS**

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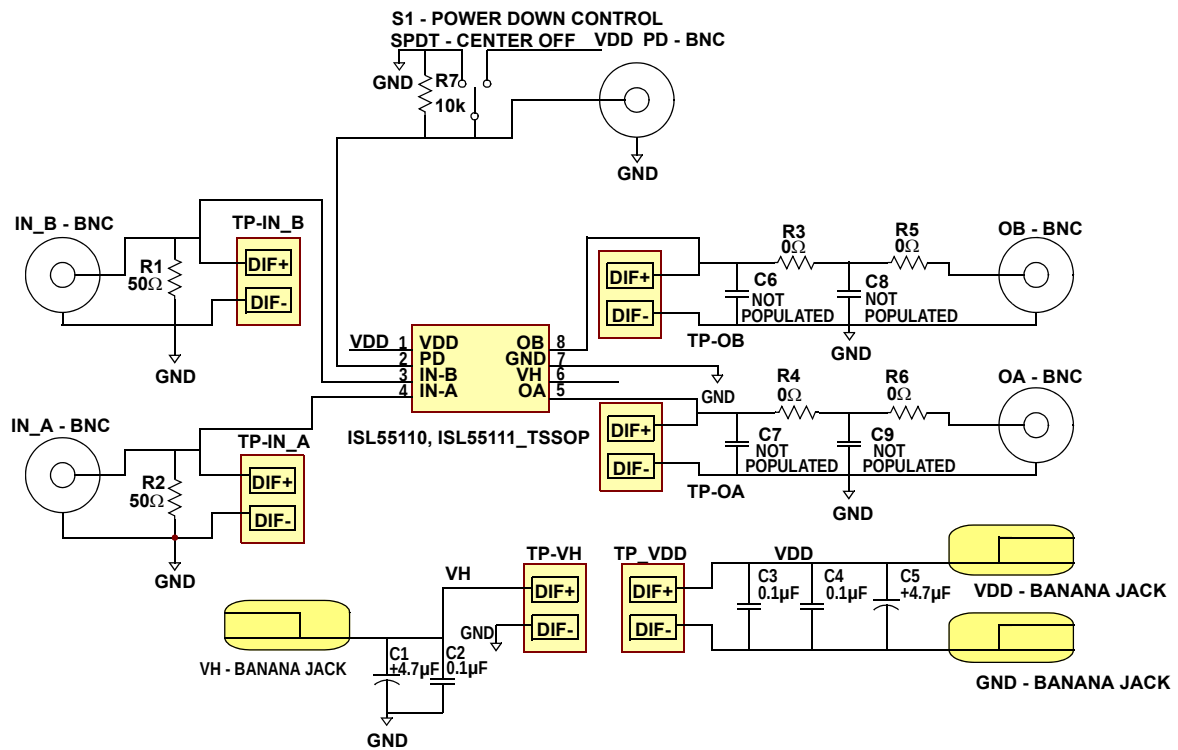


FIGURE 5. TSSOP EVALUATION BOARD SCHEMATIC

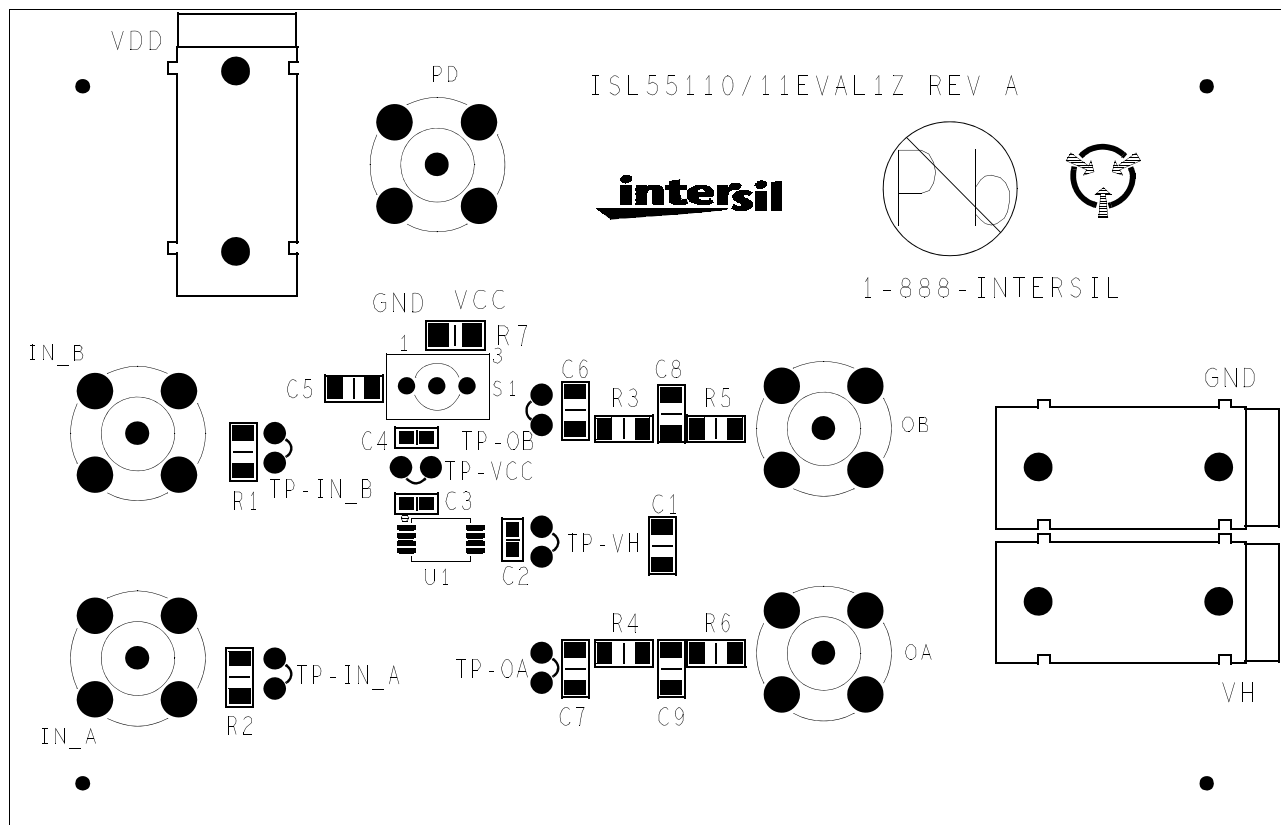


FIGURE 6. TSSOP LAYOUT

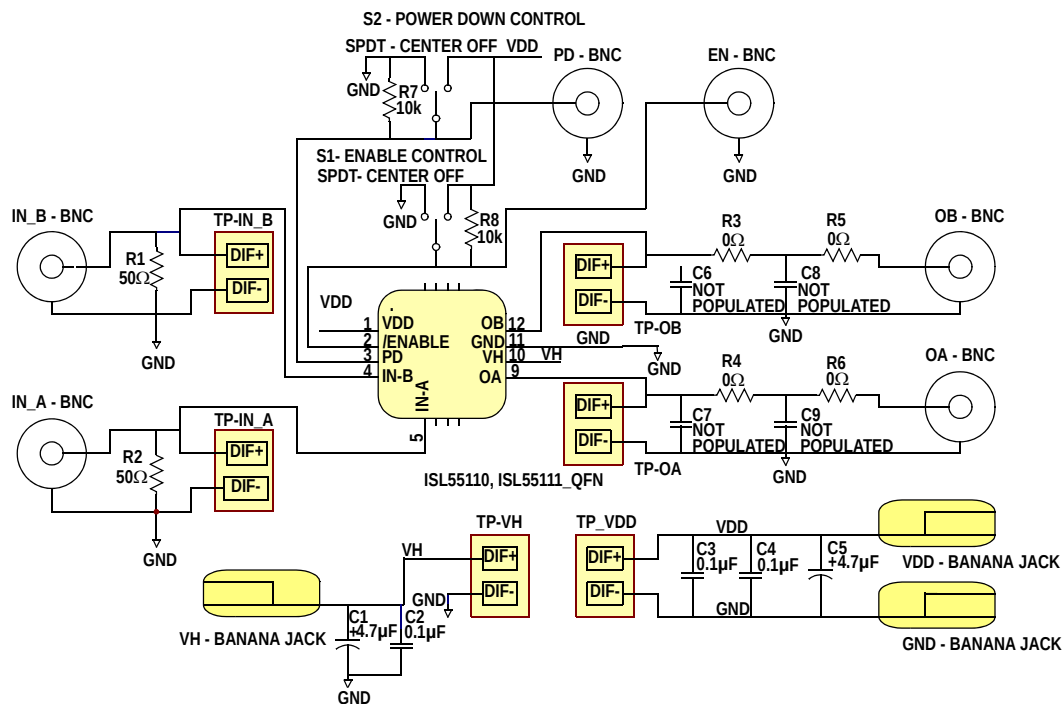


FIGURE 7. QFN EVALUATION BOARD SCHEMATIC

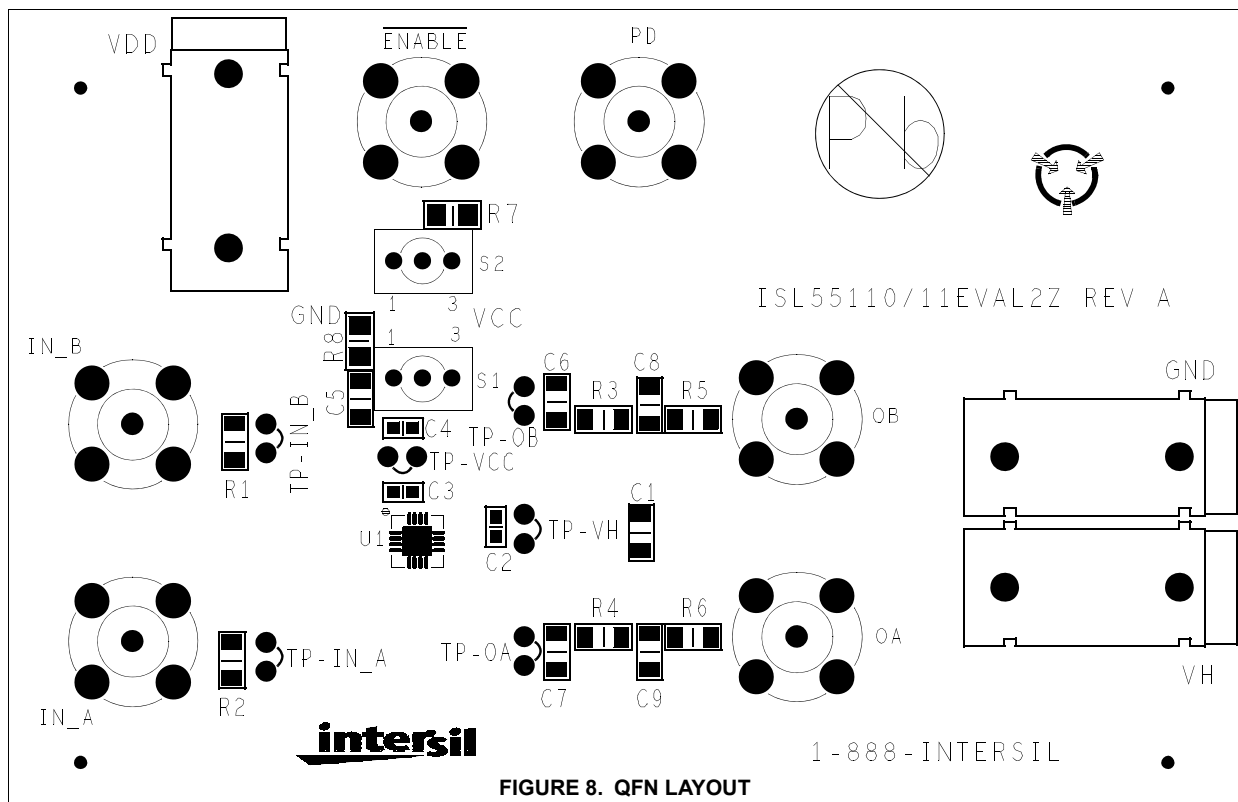


FIGURE 8. QFN LAYOUT

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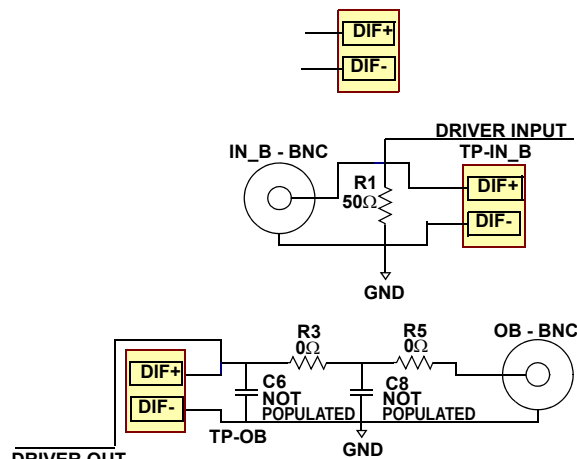


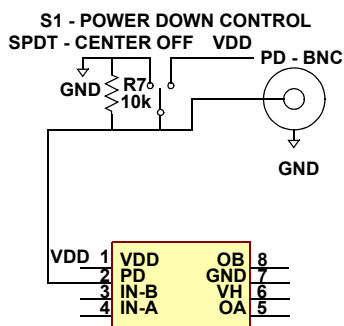
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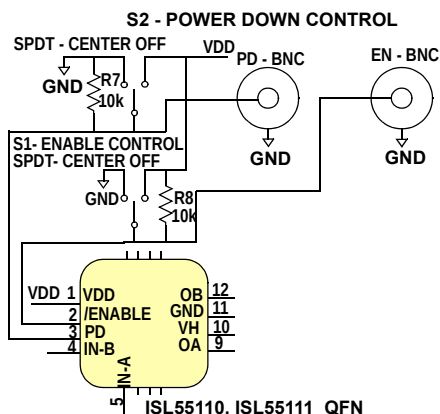
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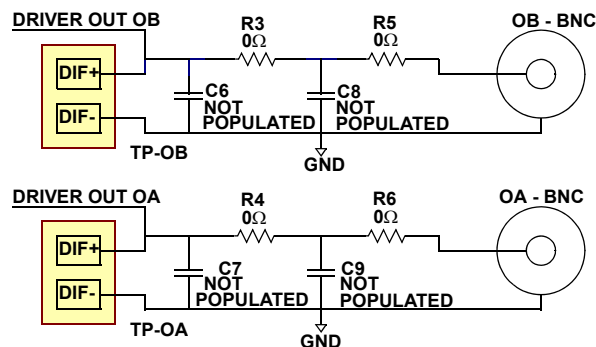
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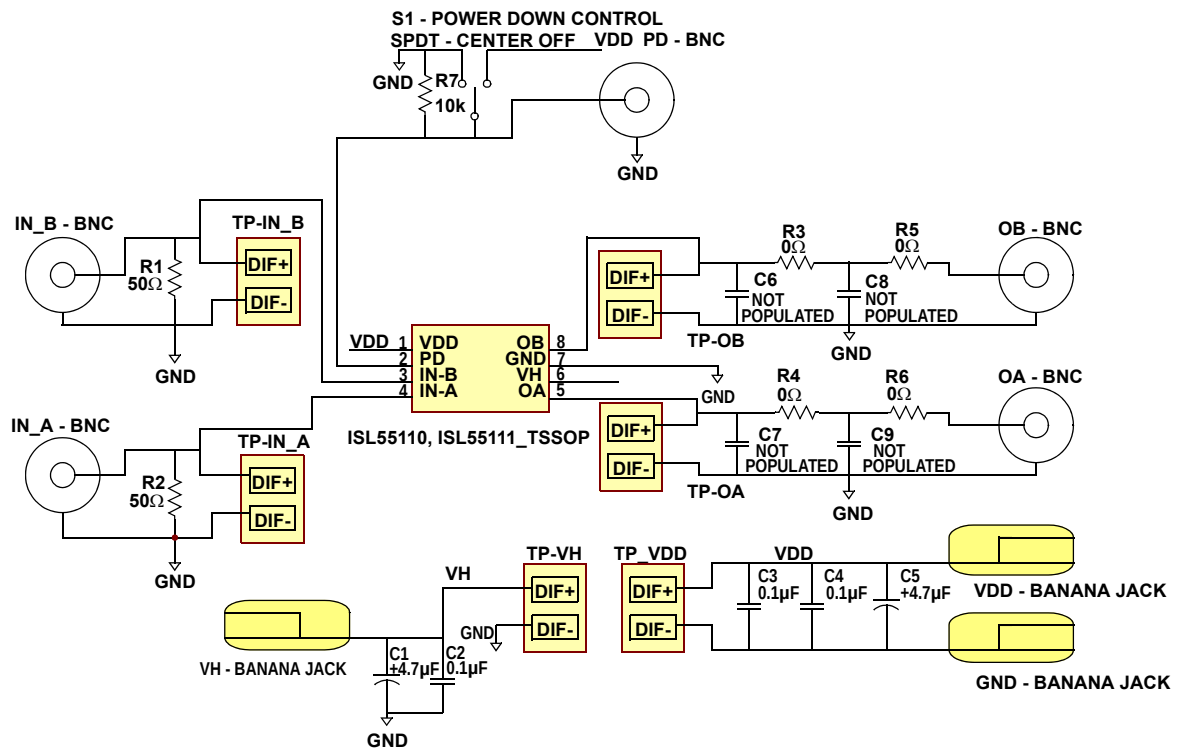


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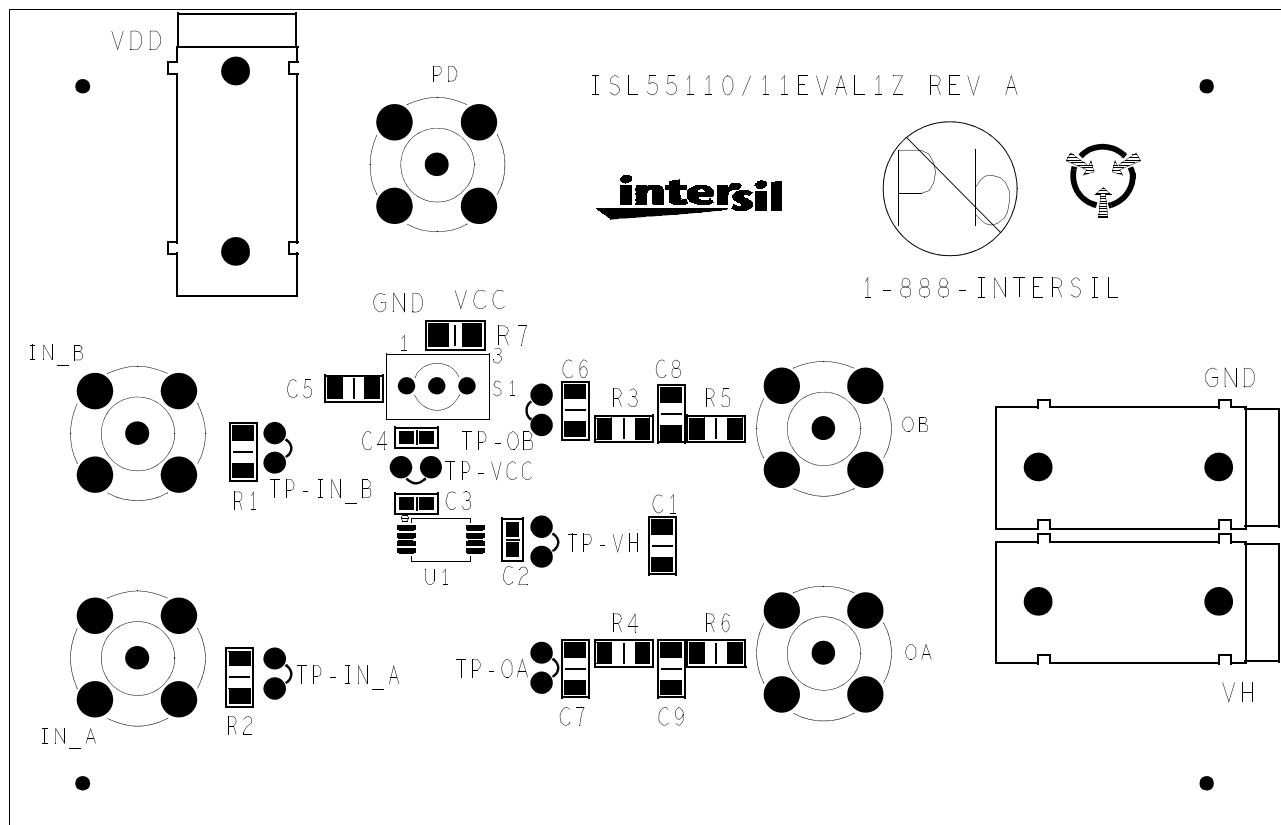


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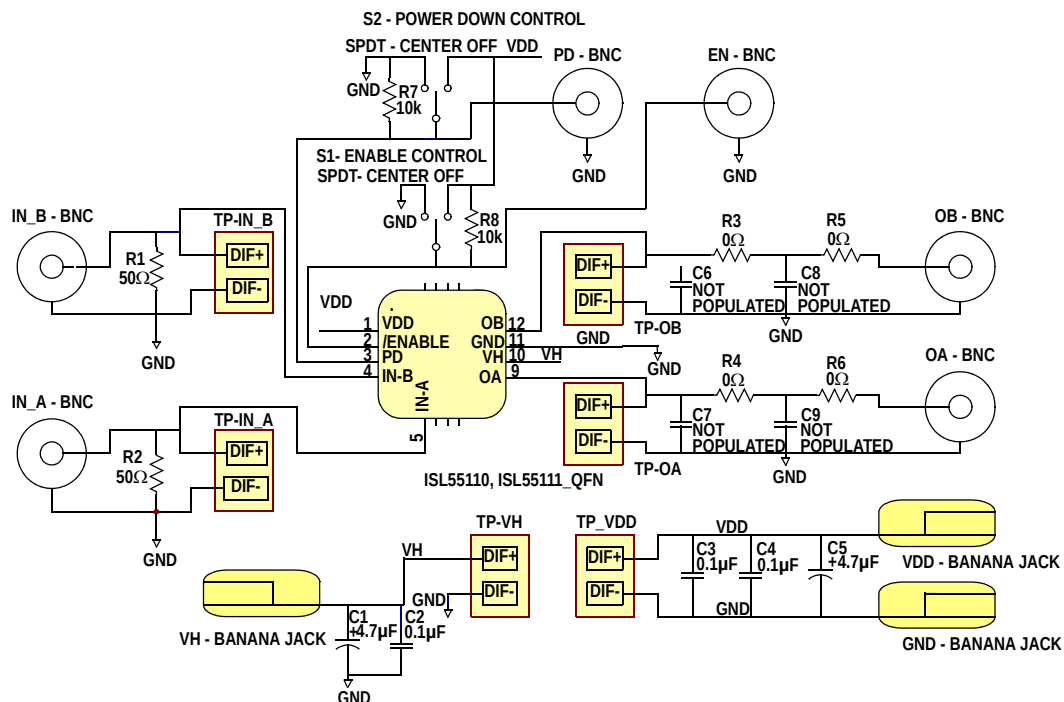


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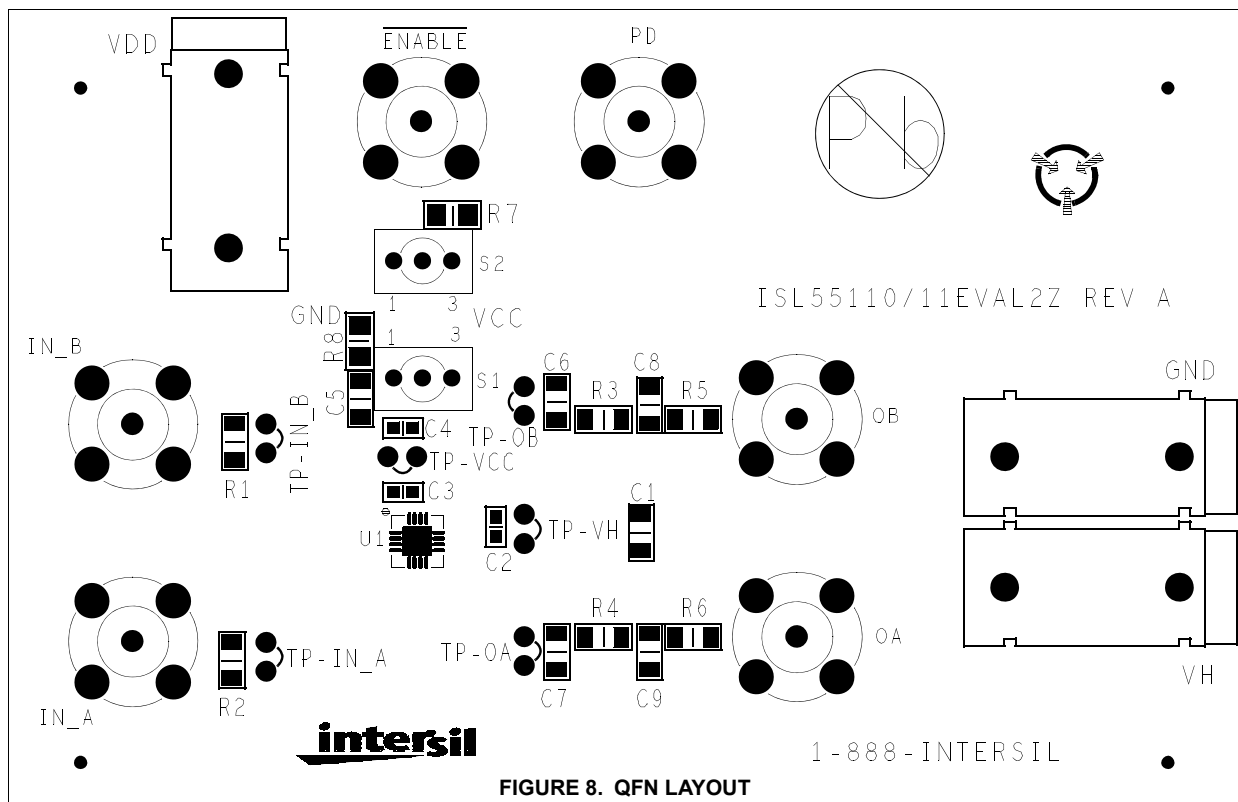


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